IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				Materials and	ials and Mfg Information			
upplier	Information													
Company name*				Company unique ID			Unique ID Authority				Response Date*			
onsemi											2025-07-16			
ontact Na	ame	Title - Conta	Title - Contact			Phone - Contact*				Email - Contact*				
roduct-E	Env-Stewards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
uthorized	l Representative*	Title - Representative			I	Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards Pro				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
		GBU4M BR GBU4L GPPN 4		N 4A 1000V		2025-07-16		TSCBE		3995.245	mg	Each		
	cturing Process Informa		F1 D	A 11 T	-STD-020 MS	U. Dating	De de Donne	D. L. T.	Mar Time	Deals Towns	None None	or of Deflect Co.		
	8		Terminal Base Alloy J-STD-CU Alloy NA			L Rating	Peak Process Body Temperature Max Time at P		· ·	ak Temperature Number of Reflow Cycles seconds 3				
	Matte Tin (Sn) - annealed		CU AHOY	I	NA		U		30	sec	collus 3			
omments														
	nformation regarding materia													

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	15.0	mg	Supplier	Silicon (Si)	7440-21-3		15	mg
Die Attach Solder	15.025		Supplier	Silver (Ag)	7440-22-4		0.3756	mg
			A	Lead (Pb)	7439-92-1	7a	13.8981	mg
			Supplier	Tin (Sn)	7440-31-5		0.7512	mg
Lead Frame	1799.6		Supplier	Iron (Fe)	7439-89-6		2.6994	mg
			Supplier	Copper (Cu)	7440-50-8		1796.0009	mg
			Supplier	Phosphorus (P)	7723-14-0		0.8998	mg
Mold Compound-Black	2160.0			Epoxy resin	proprietary data		79.92	mg
			Supplier	Phenolic Resin	Proprietary Data		79.92	mg
			Supplier	Carbon Black (C)	1333-86-4		12.96	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		324	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		151.2	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1512	mg
Plating	5.62	mg	Supplier	Tin (Sn)	7440-31-5		5.62	mg